Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs
Marketing Name / Model **[List multiple models if applicable.]**
HP ProBook 6440b Notebook PC
Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Mother board	1
Batteries	All types including standard alkaline and lithium coin or button style batteries battery and RTC battery	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LCD	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

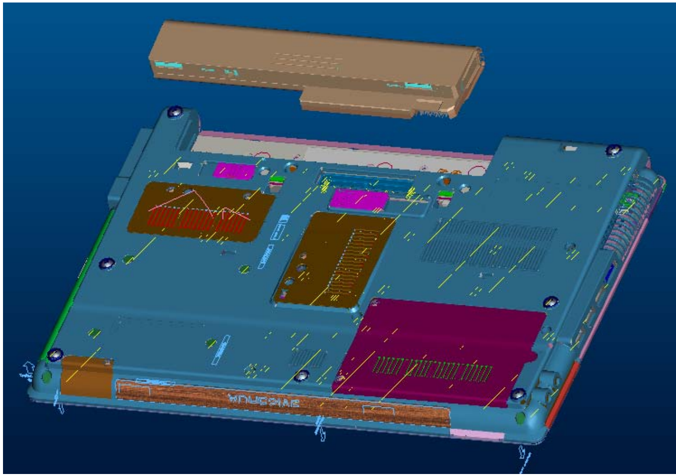
Tool Description	Tool Size (if applicable)
Description #1 screw driver	philip #1
Description #2 screw driver	Torx #T8
Description #3	
Description #4	
Description #5	

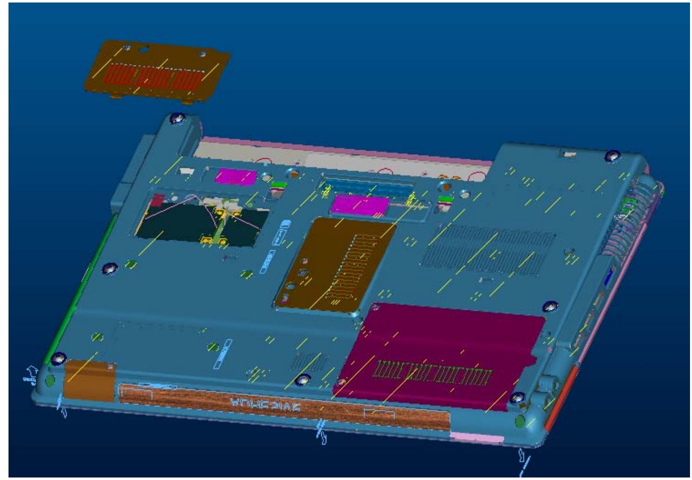
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Battery module
2. Remove Mini card door
3. Remove Ram door.
4. Remove Blue tooth door.
5. Remove Blue tooth module
6. Remove HDD door
7. Remove HDD module
8. Remove ODD assembly
9. Remove Keyboard
10. Remove strip cover (with power button PCB & Capacitive PCB)
11. Remove LCD cable and antenna
12. Divide LCD assembly from base assembly
13. Remove Palm rest sub-assemly
14. Remove TP module
15. Remove RTC Battery
16. Divide logic-up assembly(w/buttons) from base assembly
17. Remove speaker
18. Divide small PCB from base assembly
19. Remove fan module
20. Divide thermal module
21. Divide MB (with CPU and memory and thermal module) from base assembly
22. Remove RJ11 wire from lower sub-assy
23. Divide LCD cover & LCD bezel
24. Divide LCD panel and Hinge Bracket

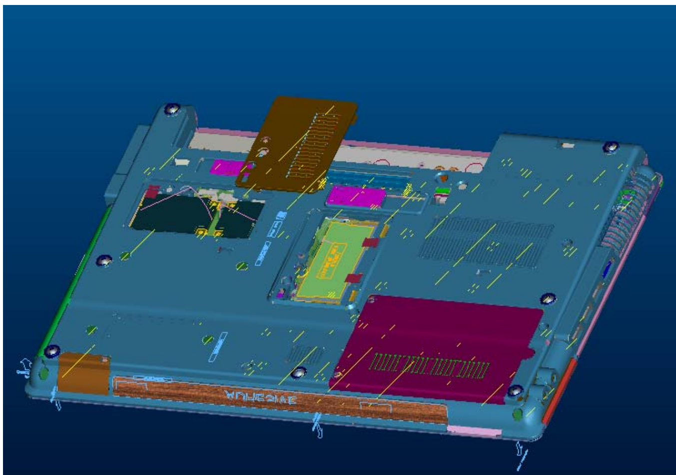
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

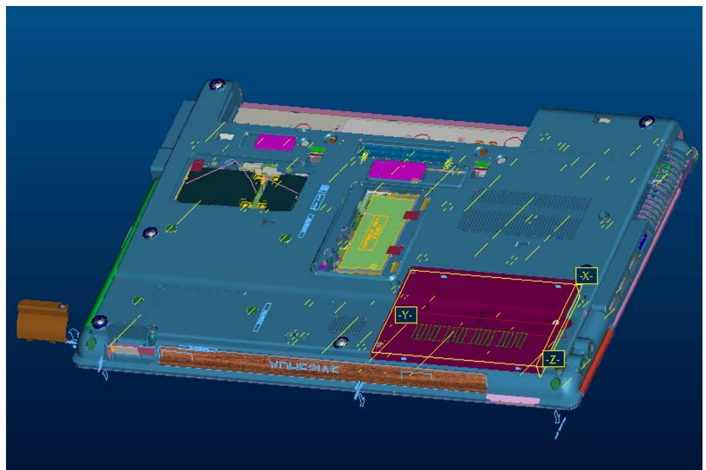




Step1.Remove Battery module

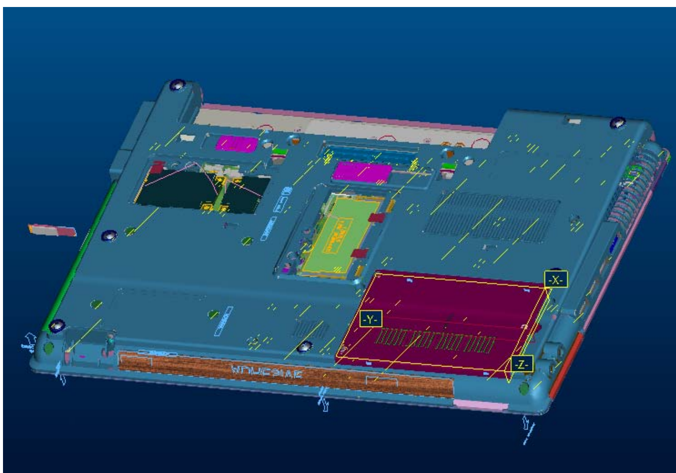
Step2.Remove Mini card door.

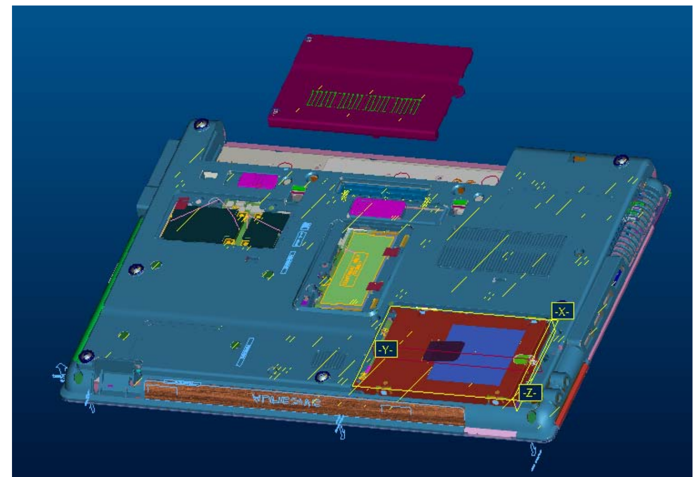




Step3. Remove Ram door.

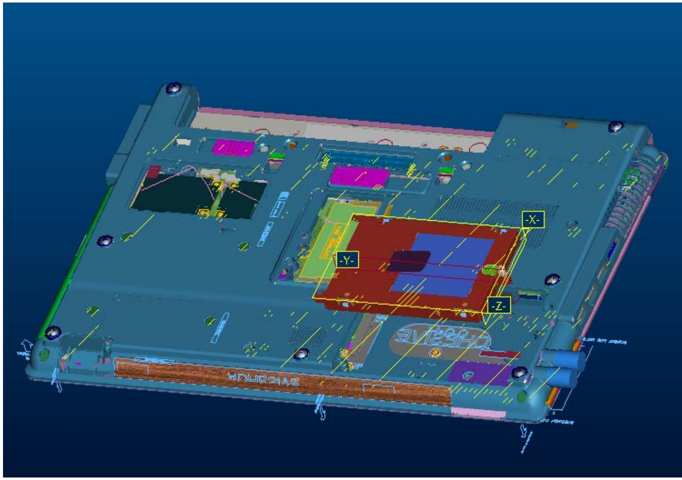
Step4. Remove Blue tooth door.



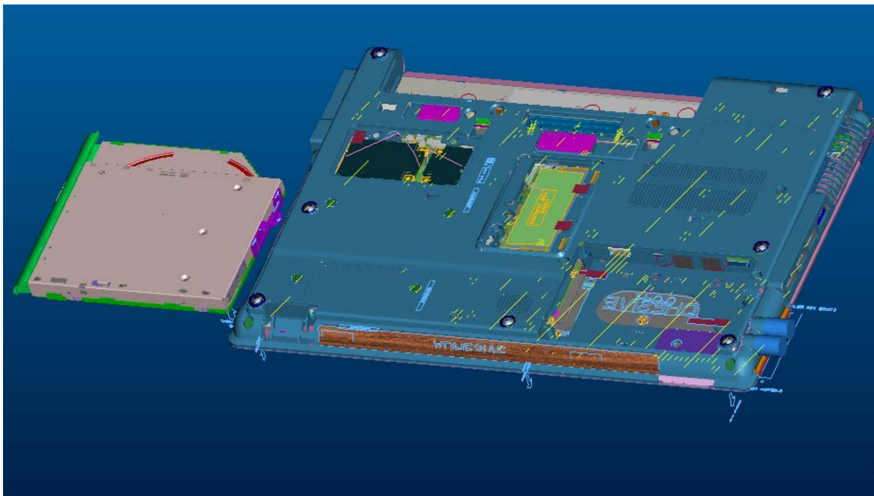


Step5. Remove Blue tooth module

Step6.Remove HDD door.

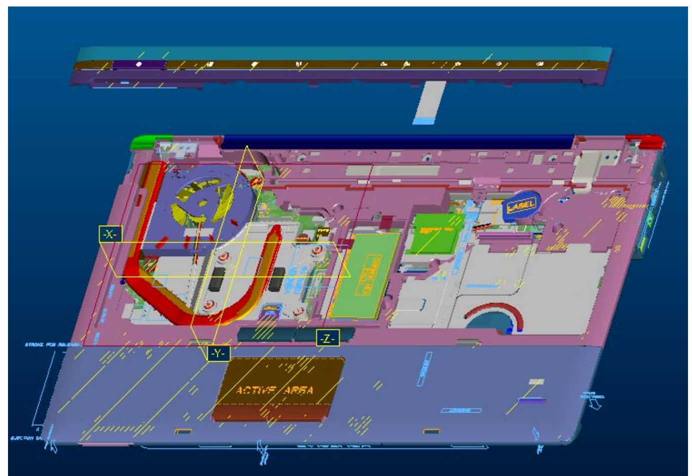


Step7.Remove HDD module

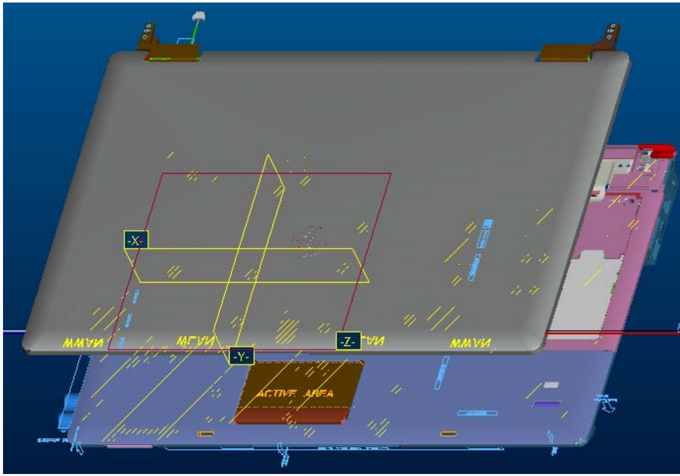


Step8. Remove ODD assembly

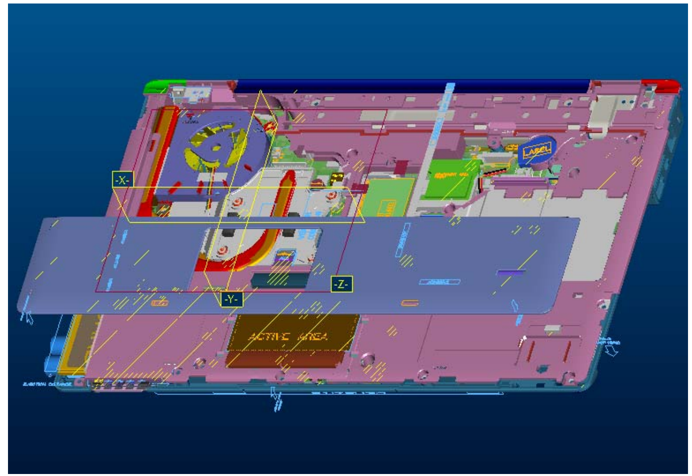
Step9. Remove Keyboard



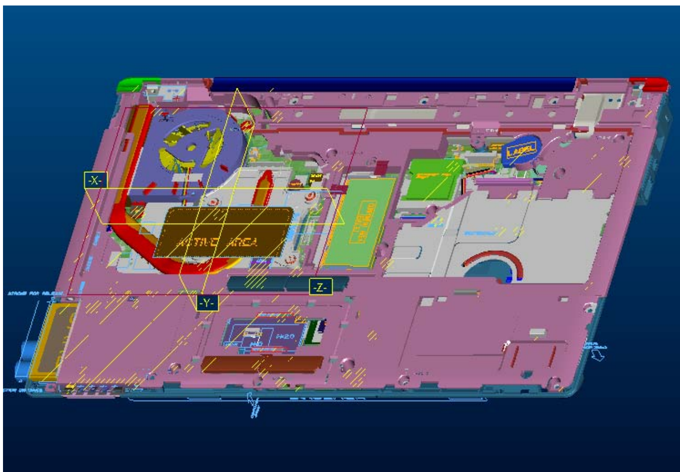
Step10. Remove strip cover



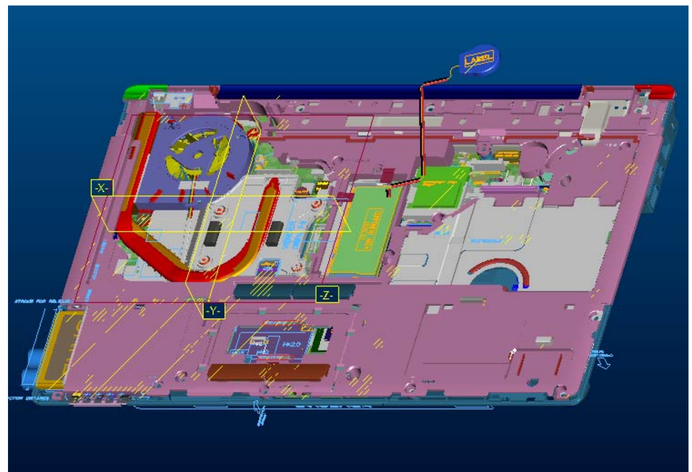
Step11~12. Remove LCD cable and antenna



Step13. Remove Palm rest sub-assemly

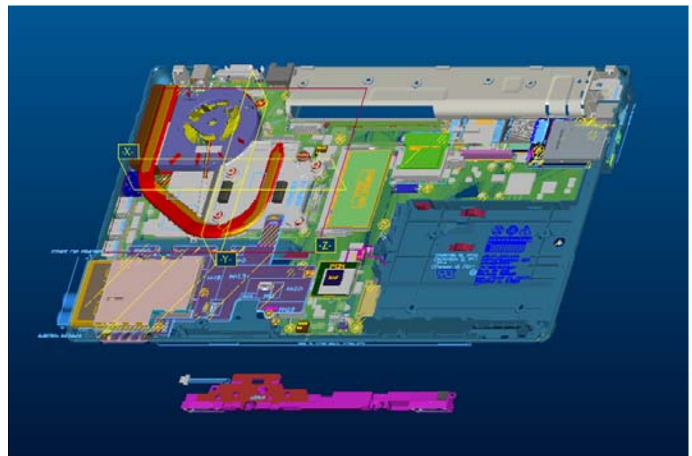


Step14.Remove TP module

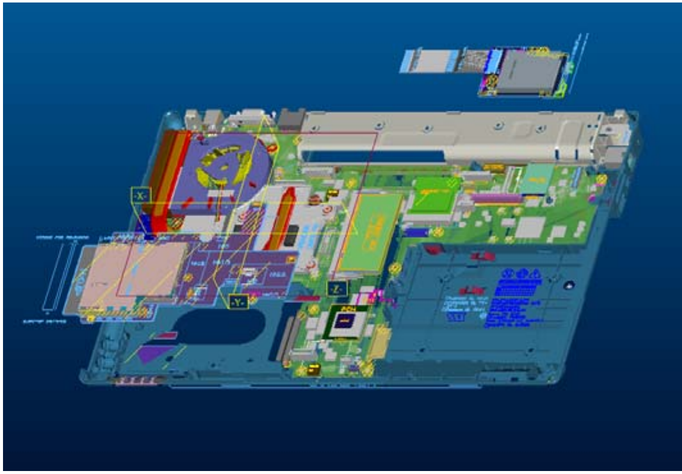


Step15. Remove RTC Battery

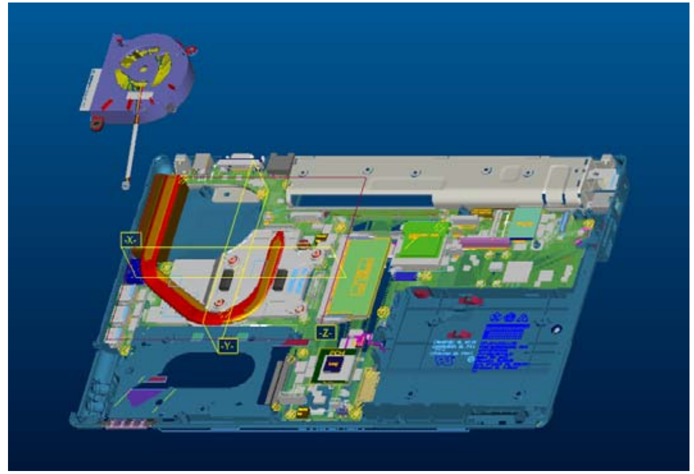
Step16. Divide logic-up assembly from base assembly



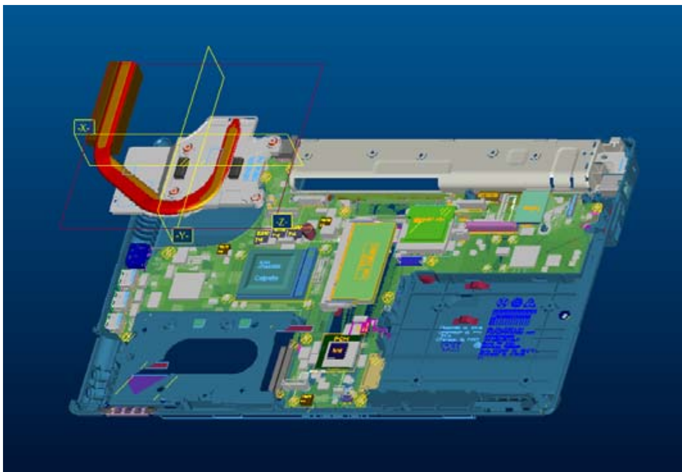
Step17. Remove speaker



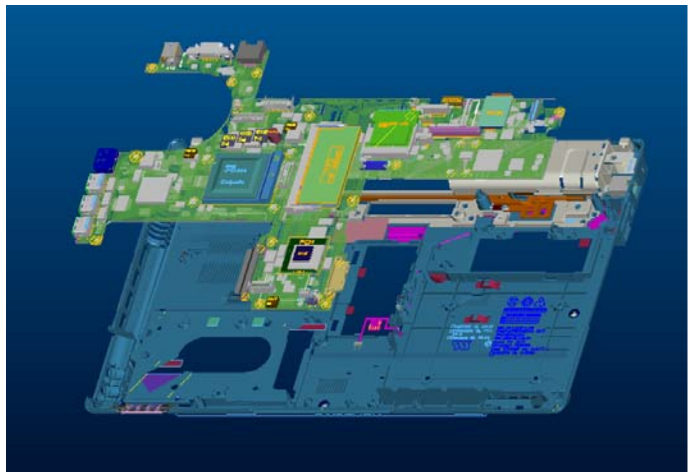
Step18. Divide small PCB from base assembly



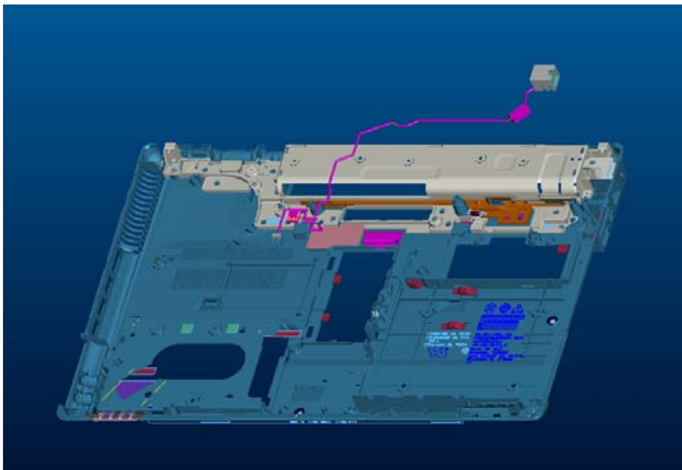
Step19.Remove fan module



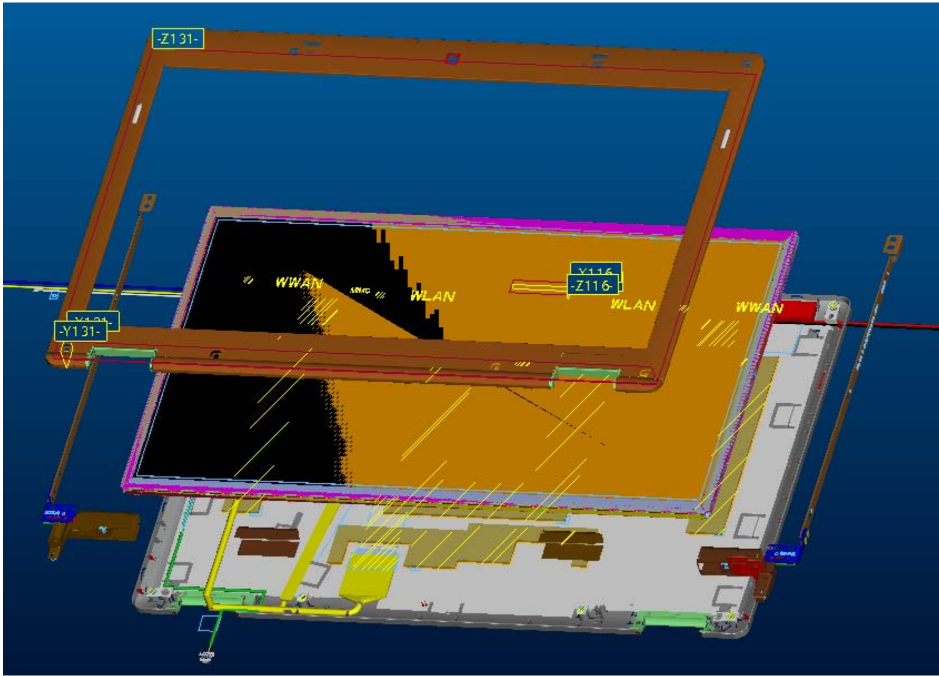
Step20. Divide thermal module



Step21. Divide MB (with CPU and memory) from base assembly



Step22. Remove RJ11 wire from lower sub-assy



Step23~24. Divide LCD cover & LCD bezel, Divide LCD panel and Hinge Bracket.